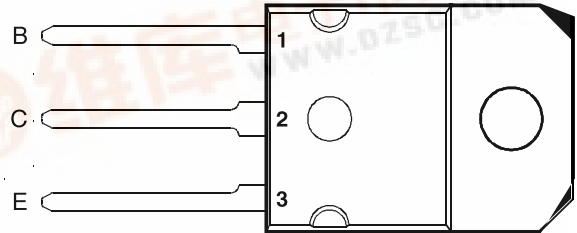




## BUV48, BUV48A NPN SILICON POWER TRANSISTORS

- Rugged Triple-Diffused Planar Construction
- 15 A Continuous Collector Current
- 1000 Volt Blocking Capability

SOT-93 PACKAGE  
(TOP VIEW)



Pin 2 is in electrical contact with the mounting base.

absolute maximum ratings at 25°C case temperature (unless otherwise noted)

RATING		SYMBOL	VALUE	UNIT
Collector-emitter voltage ( $V_{BE} = 0\text{ V}$ )	BUV48	$V_{CES}$	850	V
	BUV48A		1000	
Collector-emitter voltage ( $R_{BE} = 10\ \Omega$ )	BUV48	$V_{CER}$	850	V
	BUV48A		1000	
Collector-emitter voltage ( $I_B = 0$ )	BUV48	$V_{CEO}$	400	V
	BUV48A		450	
Continuous collector current		$I_C$	15	A
Peak collector current (see Note 1)		$I_{CM}$	30	A
Continuous base current		$I_B$	4	A
Peak base current		$I_{BM}$	20	A
Non repetitive accidental peak surge current		$I_{CSM}$	55	A
Continuous device dissipation at (or below) 25°C case temperature		$P_{tot}$	125	W
Operating junction temperature range		$T_j$	-65 to +150	°C
Storage temperature range		$T_{stg}$	-65 to +150	°C

NOTE 1: This value applies for  $t_p \leq 2\text{ ms}$ , duty cycle  $\leq 2\%$ .

# BUV48, BUV48A

## NPN SILICON POWER TRANSISTORS

### electrical characteristics at 25°C case temperature (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
$V_{CE(sus)}$ Collector-emitter sustaining voltage	$I_C = 200\text{ mA}$ $L = 25\text{ mH}$ (see Note 2) BUV48 BUV48A	400 450			V
$I_{CES}$ Collector-emitter cut-off current	$V_{CE} = 850\text{ V}$ $V_{BE} = 0$ BUV48 $V_{CE} = 1000\text{ V}$ $V_{BE} = 0$ BUV48A $V_{CE} = 850\text{ V}$ $V_{BE} = 0$ $T_C = 125^\circ\text{C}$ BUV48 $V_{CE} = 1000\text{ V}$ $V_{BE} = 0$ $T_C = 125^\circ\text{C}$ BUV48A			0.2 0.2 2.0 2.0	mA
$I_{CER}$ Collector-emitter cut-off current	$V_{CE} = 850\text{ V}$ $R_{BE} = 10\ \Omega$ BUV48 $V_{CE} = 1000\text{ V}$ $R_{BE} = 10\ \Omega$ BUV48A $V_{CE} = 850\text{ V}$ $R_{BE} = 10\ \Omega$ $T_C = 125^\circ\text{C}$ BUV48 $V_{CE} = 1000\text{ V}$ $R_{BE} = 10\ \Omega$ $T_C = 125^\circ\text{C}$ BUV48A			0.5 0.5 4.0 4.0	mA
$I_{EBO}$ Emitter cut-off current	$V_{EB} = 5\text{ V}$ $I_C = 0$			1	mA
$V_{EBO}$ Emitter-base breakdown voltage	$I_E = 50\text{ mA}$ $I_C = 0$	7		30	V
$V_{CE(sat)}$ Collector-emitter saturation voltage	$I_B = 2\text{ A}$ $I_C = 10\text{ A}$ BUV48 $I_B = 3\text{ A}$ $I_C = 15\text{ A}$ BUV48 $I_B = 1.6\text{ A}$ $I_C = 8\text{ A}$ BUV48A $I_B = 2.4\text{ A}$ $I_C = 12\text{ A}$ BUV48A (see Notes 3 and 4)			1.5 5.0 1.5 5.0	V
$V_{BE(sat)}$ Base-emitter saturation voltage	$I_B = 2\text{ A}$ $I_C = 10\text{ A}$ BUV48 $I_B = 1.6\text{ A}$ $I_C = 8\text{ A}$ BUV48A (see Notes 3 and 4)			1.6 1.6	V
$f_t$ Current gain bandwidth product	$V_{CE} = 10\text{ V}$ $I_C = 0.5\text{ A}$ $f = 1\text{ MHz}$		10		MHz
$C_{ob}$ Output capacitance	$V_{CB} = 20\text{ V}$ $I_C = 0$ $f = 1\text{ MHz}$		150		pF

NOTES: 2. Inductive loop switching measurement.

3. These parameters must be measured using pulse techniques,  $t_p = 300\ \mu\text{s}$ , duty cycle  $\leq 2\%$ .

4. These parameters must be measured using voltage-sensing contacts, separate from the current carrying contacts.

### thermal characteristics

PARAMETER	MIN	TYP	MAX	UNIT
$R_{\theta JC}$ Junction to case thermal resistance			1	°C/W

### resistive-load-switching characteristics at 25°C case temperature

PARAMETER	TEST CONDITIONS †	MIN	TYP	MAX	UNIT
$t_{on}$ Turn on time	$I_C = 10\text{ A}$ $V_{CC} = 150\text{ V}$ BUV48 $I_{B(on)} = 2\text{ A}$ $I_{B(off)} = -2\text{ A}$ (see Figures 1 and 2)			1.0	$\mu\text{s}$
$t_s$ Storage time				3.0	$\mu\text{s}$
$t_f$ Fall time				0.8	$\mu\text{s}$
$t_{on}$ Turn on time	$I_C = 8\text{ A}$ $V_{CC} = 150\text{ V}$ BUV48A $I_{B(on)} = 1.6\text{ A}$ $I_{B(off)} = -1.6\text{ A}$ (see Figures 1 and 2)			1.0	$\mu\text{s}$
$t_s$ Storage time				3.0	$\mu\text{s}$
$t_f$ Fall time				0.8	$\mu\text{s}$

† Voltage and current values shown are nominal; exact values vary slightly with transistor parameters.

### inductive-load-switching characteristics at 100°C case temperature

PARAMETER	TEST CONDITIONS †	MIN	TYP	MAX	UNIT
$t_{sv}$ Voltage storage time	$I_C = 10\text{ A}$ $I_{B(on)} = 2\text{ A}$ BUV48 $V_{BE(off)} = -5\text{ V}$ (see Figures 3 and 4)			4.0	$\mu\text{s}$
$t_{fi}$ Current fall time				0.4	$\mu\text{s}$
$t_{sv}$ Voltage storage time	$I_C = 8\text{ A}$ $I_{B(on)} = 1.6\text{ A}$ BUV48A $V_{BE(off)} = -5\text{ V}$ (see Figures 3 and 4)			4.0	$\mu\text{s}$
$t_{fi}$ Current fall time				0.4	$\mu\text{s}$

PARAMETER MEASUREMENT INFORMATION

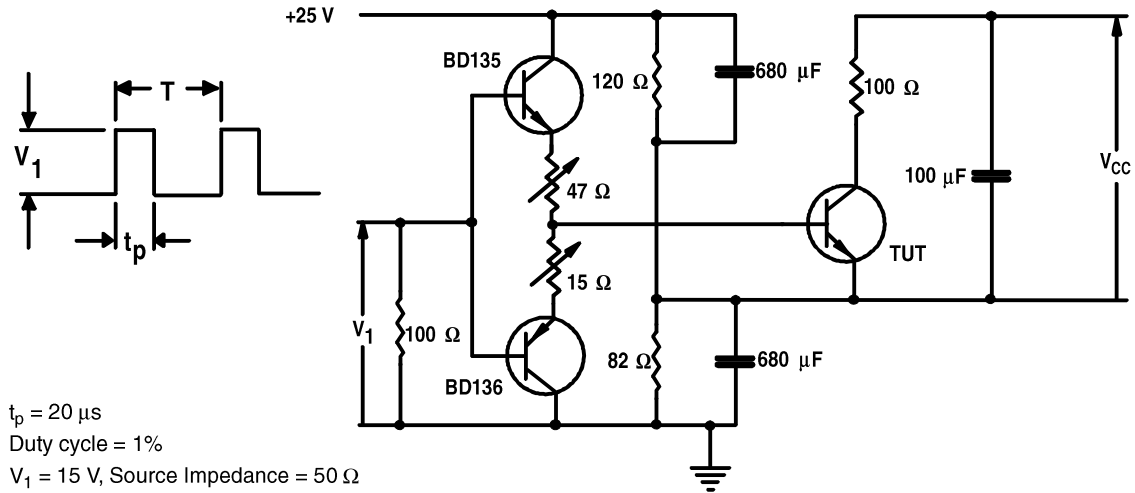


Figure 1. Resistive-Load Switching Test Circuit

- A - B =  $t_d$
- B - C =  $t_r$
- E - F =  $t_f$
- D - E =  $t_s$
- A - C =  $t_{on}$
- D - F =  $t_{off}$

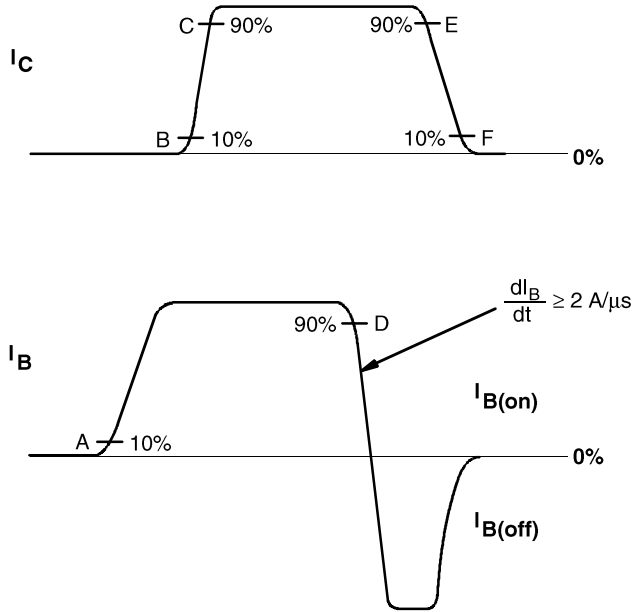


Figure 2. Resistive-Load Switching Waveform

# BUV48, BUV48A NPN SILICON POWER TRANSISTORS

## PARAMETER MEASUREMENT INFORMATION

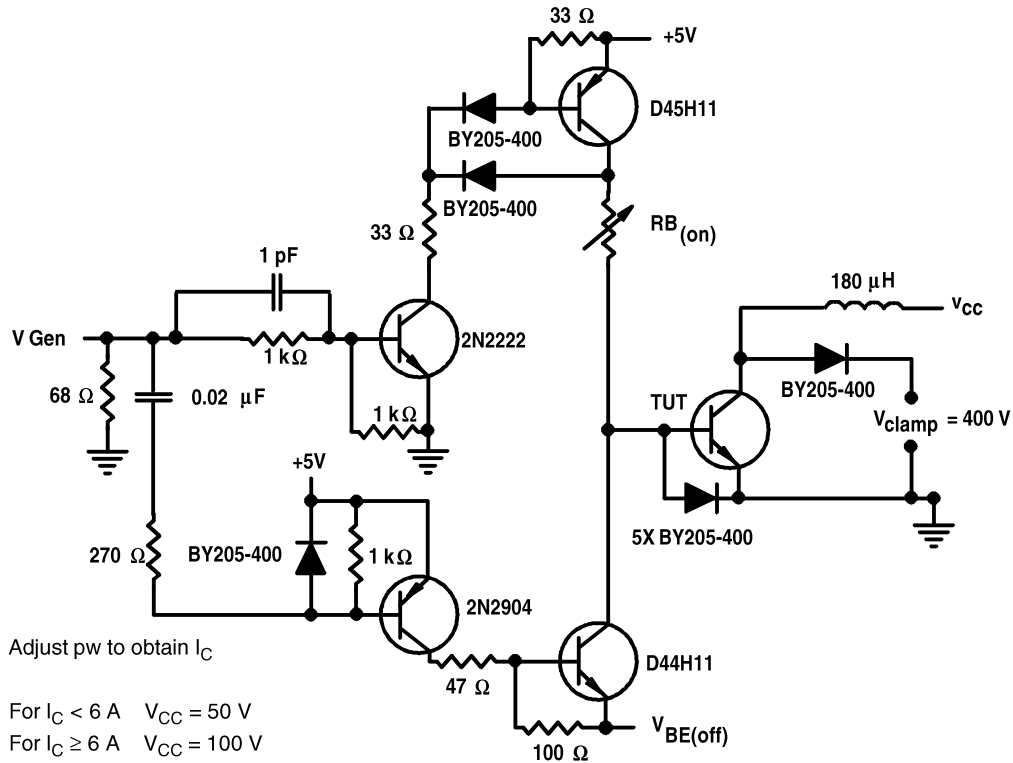
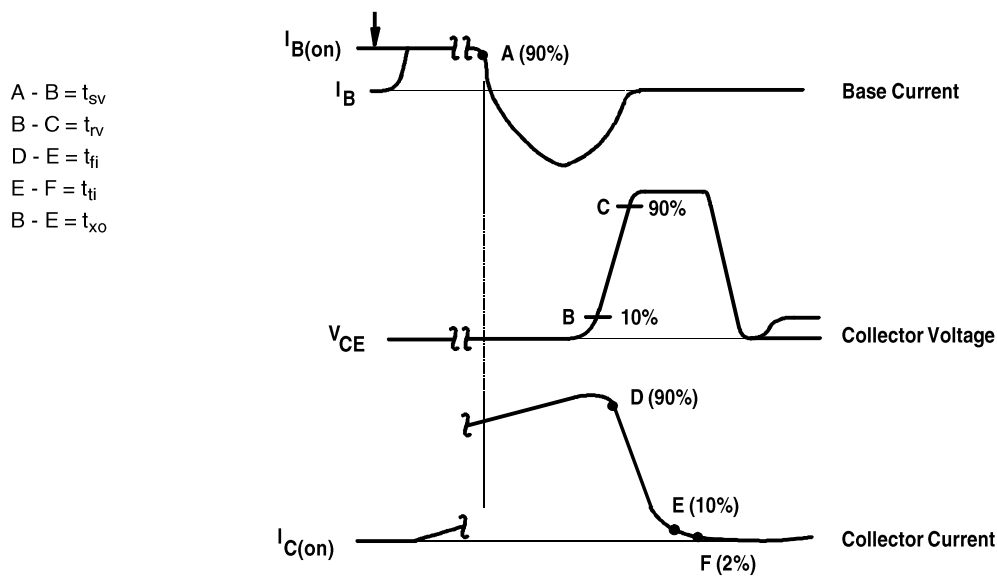


Figure 3. Inductive-Load Switching Test Circuit



NOTES: A. Waveforms are monitored on an oscilloscope with the following characteristics:  $t_r < 15 \text{ ns}$ ,  $R_{in} > 10 \Omega$ ,  $C_{in} < 11.5 \text{ pF}$ .  
 B. Resistors must be noninductive types.

Figure 4. Inductive-Load Switching Waveforms

**TYPICAL CHARACTERISTICS**

**TYPICAL DC CURRENT GAIN**  
**VS**  
**COLLECTOR CURRENT**

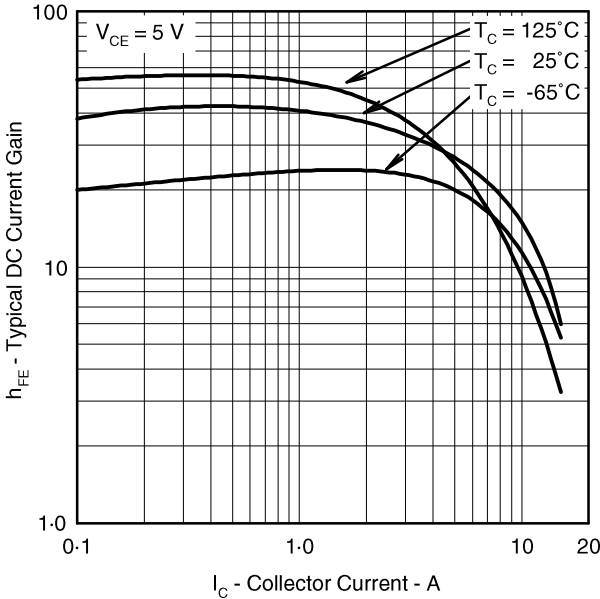


Figure 5.

**COLLECTOR-EMITTER SATURATION VOLTAGE**  
**VS**  
**BASE CURRENT**

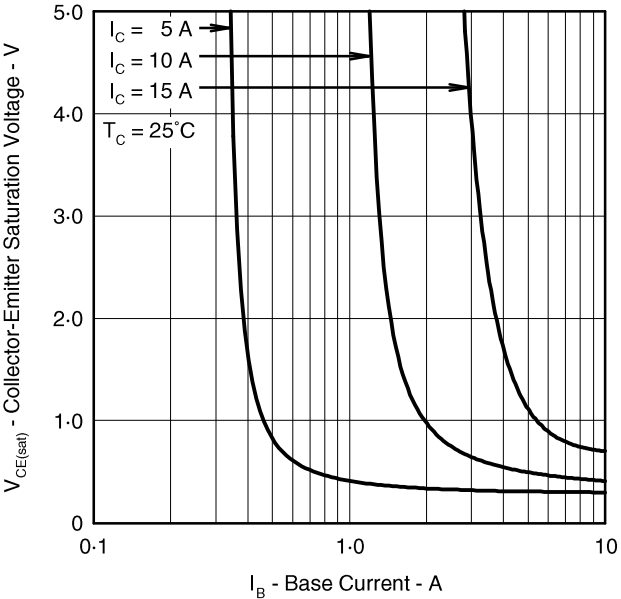


Figure 6.

**COLLECTOR-EMITTER SATURATION VOLTAGE**  
**VS**  
**BASE CURRENT**

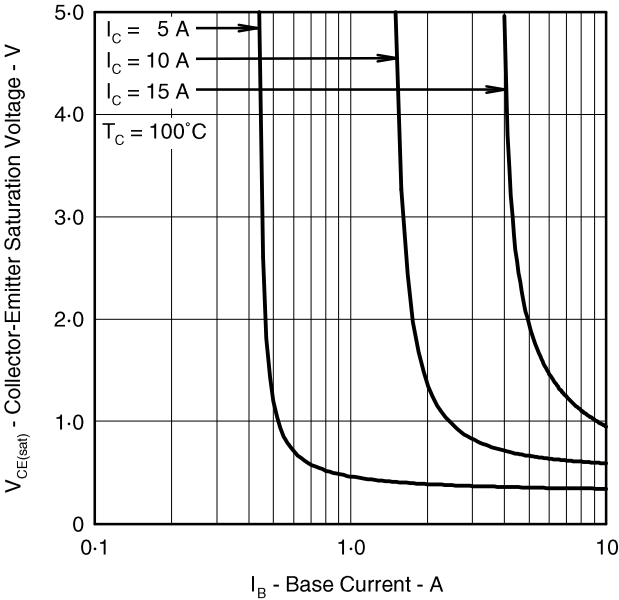


Figure 7.

**BASE-EMITTER SATURATION VOLTAGE**  
**VS**  
**BASE CURRENT**

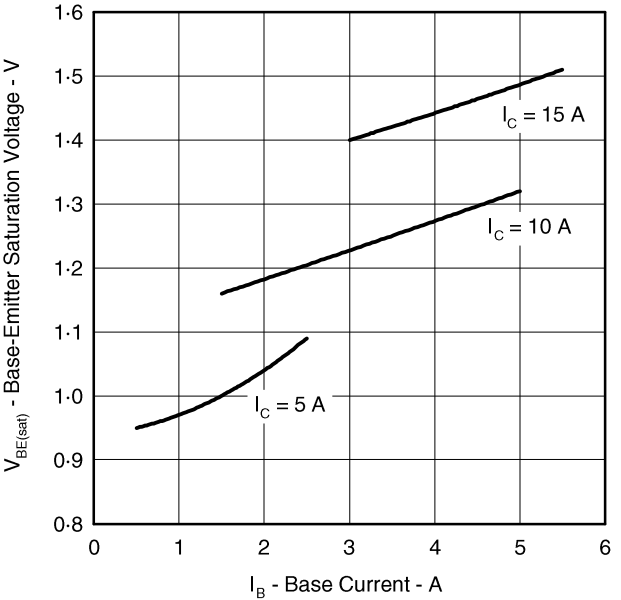


Figure 8.

**BUV48, BUV48A**  
**NPN SILICON POWER TRANSISTORS**

**TYPICAL CHARACTERISTICS**

COLLECTOR CUT-OFF CURRENT  
 VS  
 CASE TEMPERATURE

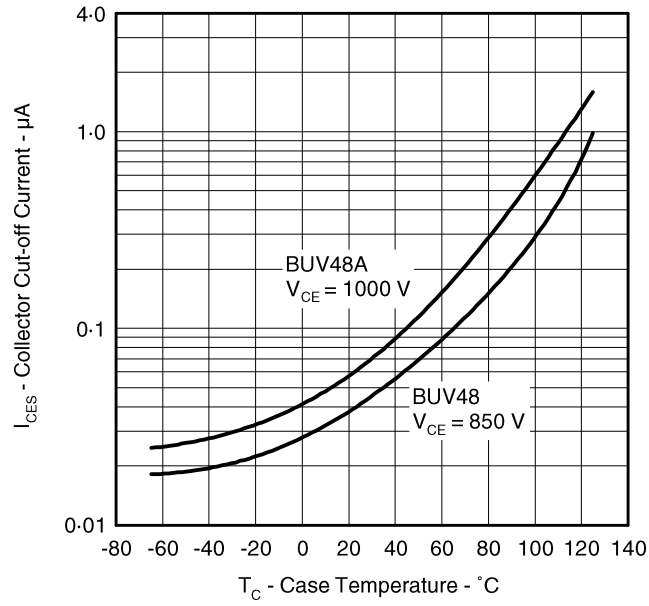


Figure 9.

**MAXIMUM SAFE OPERATING REGIONS**

MAXIMUM FORWARD-BIAS  
 SAFE OPERATING AREA

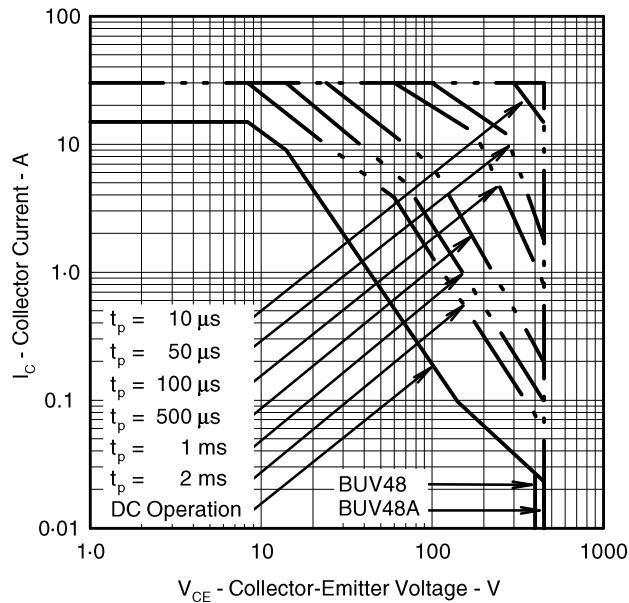


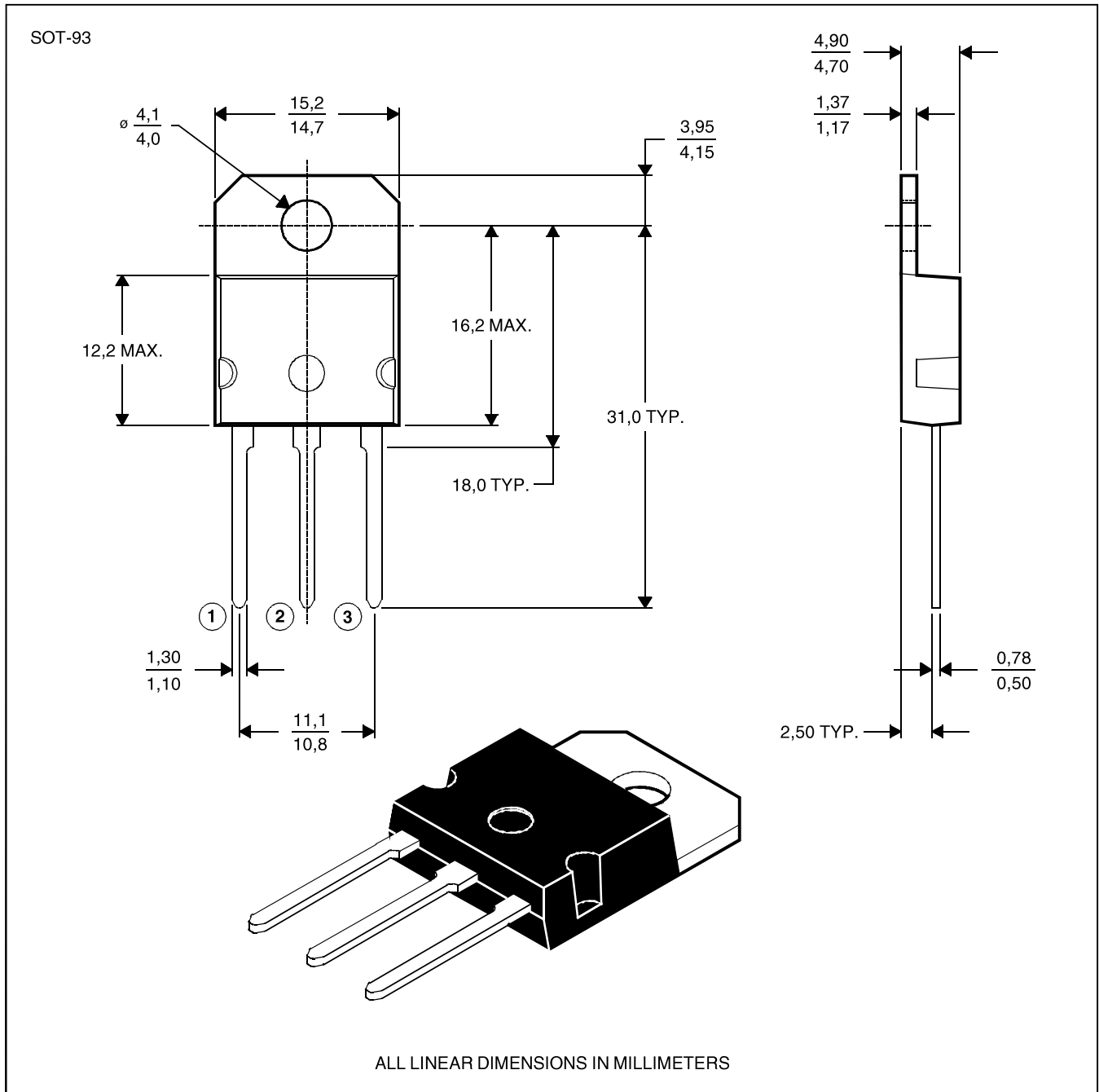
Figure 10.

MECHANICAL DATA

SOT-93

3-pin plastic flange-mount package

This single-in-line package consists of a circuit mounted on a lead frame and encapsulated within a plastic compound. The compound will withstand soldering temperature with no deformation, and circuit performance characteristics will remain stable when operated in high humidity conditions. Leads require no additional cleaning or processing when used in soldered assembly.



NOTE A: The centre pin is in electrical contact with the mounting tab.